# Specification of Thermoelectric Module TETS2-199-199-10T200-EPS-AIN

## **Description**

The TETS2-199-199-10 is a 30\*30/30\*30 mm size multistage module, it is made of selected high performance ingot and fabricated by our unique "soft" processes to achieve superior cooling/heating performance. All the dices and metallic parts are coated with a layer of thin film for anti-corrosion and oxidation in high temperature that ensure the module can work in high temperature for long life. The module is able to run million thermal cycles in 70 °C temperature change range with less 3% degrading. It is good for the need of frequently cooling and heating up to 200°C applications. If higher operation or processing temperature is required, we can design and manufacture the custom made module according to your special requirements.

#### **Features**

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

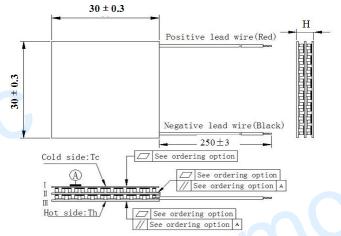
# **Application**

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

### **Performance Specification Sheet**

Th(°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>	
DT <sub>max</sub> (°C)	93	104	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U <sub>max</sub> (Voltage)	24.5	26.6	Voltage applied to the module at DT <sub>max</sub>	
I <sub>max(</sub> amps)	10.2	10.2	DC current through the modules at DT <sub>max</sub>	
Q <sub>Cmax</sub> (Watts)	98.6	108.3	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance(ohms)	2.3	2.6	The module resistance is tested under AC	
Tolerance (%)		10%	For thermal and electricity parameters	

## Geometric Characteristics Dimensions in millimeters



# **Manufacturing Options**

A. Solder:

T200: CuAgSn (M.P.= 217 ℃)

**B. Sealant:** 

EPS: Epoxy sealant

C. Ceramics:

AlN: Aluminum Nitride

**D. Ceramics Surface Options:** 

Blank ceramics (not metalized)

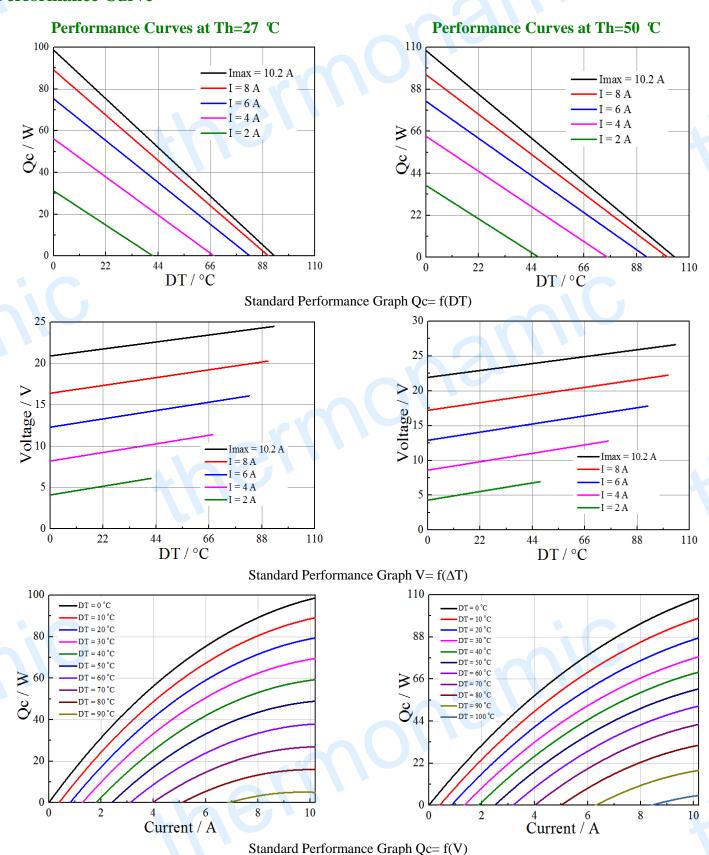
# **Ordering Option**

Suffix	Thickness (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0:4.9±0.2	0:0.08/0.08	250±3/Specify

## **Operation Cautions**

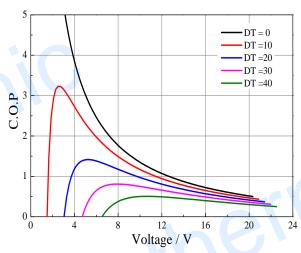
- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I<sub>max</sub> or V<sub>max</sub>
- Work under DC

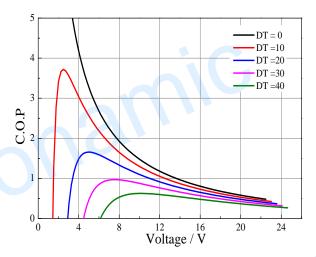
#### **Performance Curve**



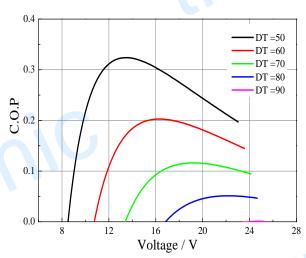


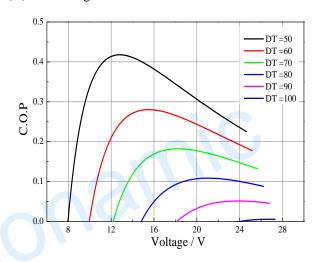






Standard Performance Graph COP = f(V) of  $\Delta T$  ranged from 0 to 30 °C



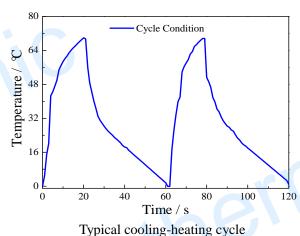


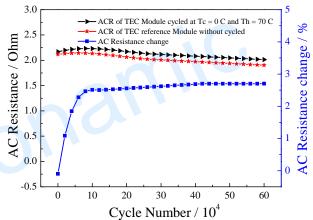
Standard Performance Graph COP = f(V) of  $\Delta T$  ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V ×I).

A typical 127 couples module is fabricated by the unique "soft" process and has demonstrated that it only has 2.5% degrading after 300,000 thermal cycling. The below graphic shows that in beginning 120,000 cycles, it degrade about 2.5%, and then go on stable with very tiny degrading in further 380,000 thermal cycles. It is derived out that the modules can go over million thermal cycles.

# **TEC Thermal Cycle Lifetime Test On TETC1-12706**





The Chart for AC Resistance and AC Resistance Changes

vs Cycle Number